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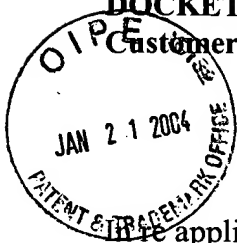
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DAC

DOCKET NO. 93-C-077C1 (STMI01-93077)

PATENT

Customer No. 30425



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: : Loi N. Nguyen, et al.

Serial No. : 09/712,827

Filed : November 14, 2000

For : METHOD AND INTERLEVEL DIELECTRIC
STRUCTURE FOR IMPROVED METAL STEP
COVERAGE

Group No. : 2814

Examiner : L. Pham

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

Sir:

The undersigned hereby certifies that the following documents:

1. Petition Under 37 C.F.R. §1.181;
2. A postcard receipt;

relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on 1/15/04.

Date: 1/15/04

Date: 1-15-04

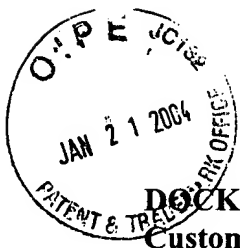
Kathy Cedar

Mailer

Daniel E. Venglarik

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DOCKET NO. 93-C-077C1 (STMI01-93077)
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PATENT

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Group No. : 2814
Examiner : L. Pham

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

PETITION UNDER 37 C.F.R. § 1.181

Pursuant to 37 C.F.R. § 1.181(a)(3), Applicants respectfully invoke the supervisory authority of the Commissioner with respect to consideration of the references cited by Applicants in an Information Disclosure Statement filed March 27, 2001.

An Information Disclosure Statement was filed by Applicants pursuant to 37 C.F.R. § 1.56 on March 27, 2001. The Information Disclosure Statement was properly filed with a Form PTO-1449 listing all cited references and copies of each reference cited.

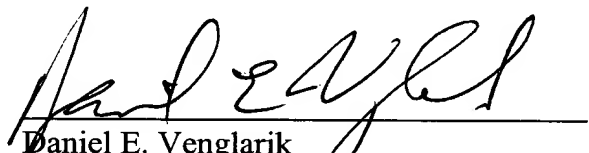
Applicants have unsuccessfully attempted to obtain an initialed Form PTO-1449 for the Information Disclosure Statement indicating consideration of the cited references. Consideration of the cited references and an initialed Form PTO-1449 are respectfully requested.

The Commissioner is hereby authorized to charge any additional fees connected with this communication or credit any overpayment to Deposit Account No. 50-0208.

Respectfully submitted,

DAVIS MUNCK, P.C.

Date: 1-15-04


Daniel E. Venglarik
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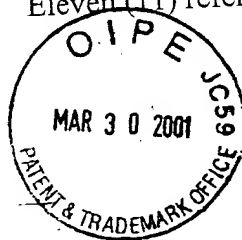
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Tel: (972) 628-3600
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Mailed: March 27, 2001
In re. Application of: Loi N. Nguyen, et al
Serial No.: 09/712,827
Filing Date: November 14, 2000
Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR
IMPROVED METAL STEP COVERAGE
Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the date stamped below:

- 1) Information Disclosure Statement;
- 2) Form PTO-1449; and,
- 3) Eleven (11) references as cited on Form PTO-1449.



DOCKETED
APR 08 2001

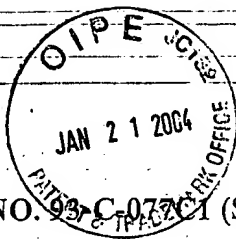
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APR - 4 2001
NOVAKOV DAVIS & MUNCK



Mailed: March 27, 2001
In re. Application of: Loi N. Nguyen, et al
Serial No.: 09/712,827
Filing Date: November 14, 2000
Title: METHOD AND INTERLEVEL DIELECTRIC STRUCTURE FOR
IMPROVED METAL STEP COVERAGE
Docket No.: 93-C-077C1 (STMI01-93077)

The following documents were received in the U.S. Patent and Trademark Office on the date stamped below:

- 1) Information Disclosure Statement;
- 2) Form PTO-1449; and,
- 3) Eleven (11) references as cited on Form PTO-1449.



DOCKET NO. 93-C-0731 (STMI01-93077)

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Loi N. Nguyen, et al.
U.S. Serial No. : 09/712,827
Filed : November 14, 2000
For : METHOD AND INTERLEVEL DIELECTRIC STRUCTURE
FOR IMPROVED METAL STEP COVERAGE
Group No. : 2835
Examiner : (Not Yet Known)

Commissioner of Patents
and Trademarks
Washington, D. C. 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 3/27/01 (Date)

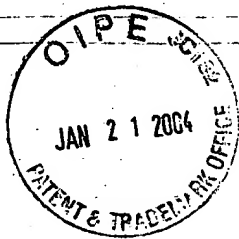
KATHY LONGENECKER
(Printed or typed name of person signing the certificate)

Kathy Longenecker
(Signature of the person signing the certificate)

Dear Sir:

INFORMATION DISCLOSURE STATEMENT

Pursuant to the duty of disclosure under 37 C.F.R. § 1.56, Applicant submits this statement. This submittal is made in accordance with 37 C.F.R. §§ 1.97 and 1.98 and § 609 of the Manual of Patent Examining Procedure. The patents, publications and other information herein are listed below and on the attached Form PTO-1449. Copies of the listed references are submitted herewith.



DOCKET No. 93-C-077C1 (STMI01-93077)
U.S. SERIAL No. 09/712,827
PATENT

<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Date</u>
4,686,000	Heath	Aug. 11, 1987
4,824,767	Chambers, et al.	Apr. 25, 1989
5,063,176	Lee, et al.	Nov. 5, 1991
5,166,088	Ueda, et al.	Nov. 24, 1992
5,266,516	Ho	Nov. 30, 1993

<u>Foreign Patent No.</u>	<u>Country</u>	<u>Date</u>
JP60246675	Japan	December 6, 1985
JP4196486	Japan	July 16, 1992
0 523 856 A2	Europe	January 20, 1993
JP5074958	Japan	March 26, 1993
0 534 130 A1	Europe	March 31, 1993

Publications

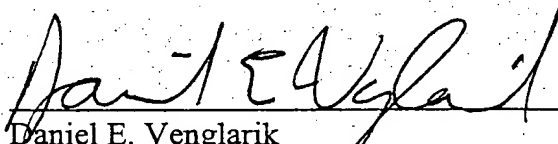
"VLSI Fabrication Principles," by Sorab K. Ghandhi, Rensselaer Polytechnic Institute, A Wiley-Interscience Publication, 1983, pages 479-482; 499-501.

Applicant hereby expressly reserves the right to swear behind the effective dates of any of the above Patents and to question the relevance and materiality of the Patents and Publications listed herein, in whole, in part, or in combination, subsequent to filing this Information Disclosure Statement.

Respectfully submitted,

NOVAKOV DAVIS & MUNCK, P.C.

Date: 3-27-01


Daniel E. Venglarik
Registration No. 39,409

DOCKET No. 93-C-077C1 (STMI01-93077)
U.S. SERIAL No. 09/712,827
PATENT

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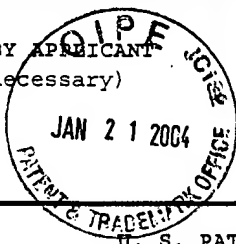
FORM PTO-1449
(REV. 7.80)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO.
93-C-077C1 (STMI01-93077)

SERIAL NO.
09/712,827

LIST OF REFERENCES CITED BY APPLICANT
(Use several sheets if necessary)



APPLICANT
Loi N. Nguyen, et al.

FILING DATE
November 14, 2000

GROUP
2835

U. S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	AA	4,686,000	08/11/1987	Heath	156	643	Feb. 19, 1986
	AB	4,824,767	04/25/1989	Chambers, et al.	430	313	Jun. 2, 1987
	AC	5,063,176	11/05/1991	Lee, et al.	437	195	May 30, 1990
	AD	5,166,088	11/24/1992	Ueda, et al.	437	47	Jun. 25, 1991
	AE	5,266,516	11/30/1993	Ho	437	57	Jan. 2, 1992
	AF						
	AG						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AH	0 523 856 A2	06/28/91	Europe				
	AI	0 534 130 A1	3/31/93	Europe				
	AJ	JP60246675	06/12/85	Japan				
	AK	JP4196486	07/16/92	Japan				
	AL	JP5074958	03/26/93	Japan				
	AM							

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

	AN	"VLSI Fabrication Principles," by Sorab K. Ghandhi, Rensselaer Polytechnic Institute, A Wiley-Publication, John Wiley & Sons, 1983, pages 479-482, 499-501.
	AO	
	AP	

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line if not in conformance and not considered. Include copy of this form with next communication to applicant.